

60V N-Channel Split Gate MOSFET

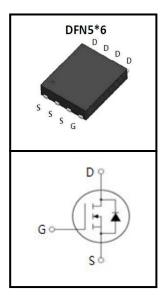
FEATURES

- Trench Power MOSFET Technology
- Low Rds(ON)
- Low Gate Charge
- Optimized For Fast-switching Applications

APPLICATIONS

- ●DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification





Device Marking and Package Information				
Device	Package	Marking		
CSN06N3P6	DFN5*6	CSN06N3P6		

Absolute Maximum Ratings at T _j = 25°C unless otherwise noted					
Parameter	Symbol	Value	Unit		
Drain-Source Voltage (V _{GS} = 0V)	V_{DSS}	60	V		
Continuous Drain Current T _C = 25°C		100	Α		
Continuous Drain Current T _C = 100°C	I _D	75	Α		
Pulsed Drain Current (note1)	I _{DM}	240	Α		
Gate Source Voltage	V _{GSS}	±20	V		
Single Pulse Avalanche Energy (note2)	E _{AS}	101	mJ		
Power Dissipation T _C = 25°C	P _D	83	W		
Operating Junction and Storage Temperature Range	T_J , T_{stg}	-55~+175	°C		

Thermal Characteristics			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta Jc}$	1.5	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	45	°C/W
Thermal Resistance, Junction-ambient	$R_{\theta JA}$	55	



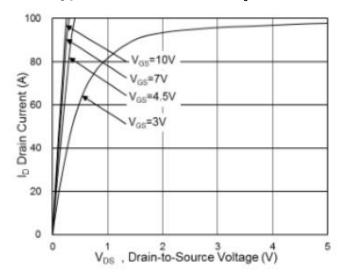
Electrical Characteristics T	_j = 25°C ur	nless otherwise specified					
Power stars	Or make all	To at Oo wellstone	Value			11.24	
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_{D} = 250\mu A$	60			V	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 48V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	uA	
Zero Gate Voltage Brain Garrent	DSS	V _{DS} = 48V, V _{GS} = 0V, T _J = 125°C			5	uA	
Gate-Source Leakage	I _{GSS}	$V_{GS} = \pm 20V$			±100	nA	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.2		2.3	V	
Davis Course On Desistance		V _{GS} = 10V, I _D = 20A		3.0	3.6	mΩ	
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 4.5V, I _D = 15A		4.4	5.4		
		Dynamic					
Input Capacitance	C _{iss}	$V_{GS} = 0V$,		3450			
Output Capacitance	C _{oss}	$V_{DS} = 30V$,		1522		pF	
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		22			
Total Gate Charge (4.5V)	Q_g			58			
Gate-Source Charge	Q_{gs}	$V_{DS} = 30V, I_{D} = 20A,$ $V_{GS} = 4.5V$		16		nC	
Gate-Drain Charge	Q_{gd}	. 35		4			
Turn-on Delay Time	t _{d(on)}			18			
Turn-on Rise Time	t _r	$V_{DD} = 30V, I_{D} = 1A,$		8		no	
Turn-off Delay Time	t _{d(off)}	$V_{GS} = 30V, R_G = 3.3\Omega$		50		ns	
Turn-off Fall Time	t _f			10.5			
	Во	dy Diode Characteristics					
Source-Drain Current(Body Diode)	I _S				100	А	
Pulsed Source Curren	I _{SDM}	$V_{G=}V_{D} = 0V$, Force Current			240		
Body Diode Voltage	V _{SD}	$T_J = 25^{\circ}\text{C}, I_{SD} = 1\text{A}, V_{GS} = 0\text{V}$			1.2	V	

Notes

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width $\leqq\!300\text{us}$, duty cycle $\leqq\!2\%$
- 3. The EAS data shows Max. rating . The test condition is VDD =25V,VGS =10V,L=0.5mH $\,$
- 4. The power dissipation is limited by 175°C junction temperature
- 5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.



Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted



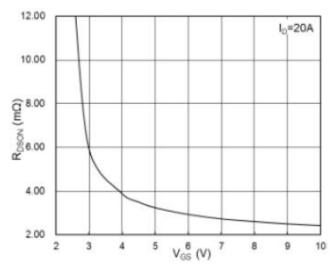


Fig.1 Typical Output Characteristics

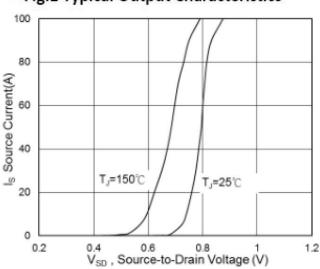


Fig.2 On-Resistance v.s Gate-Source

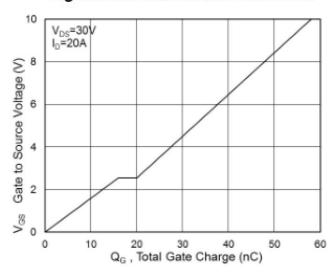


Fig.3 Forward Characteristics of Reverse diode

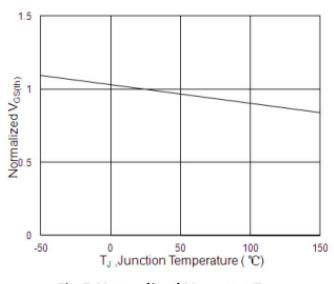


Fig.5 Normalized V_{GS(th)} v.s T_J

Fig.4 Gate-Charge Characteristics

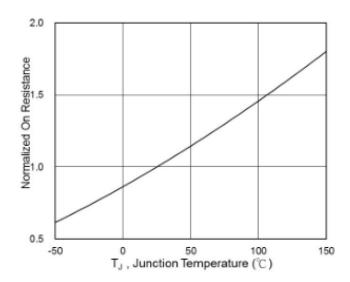
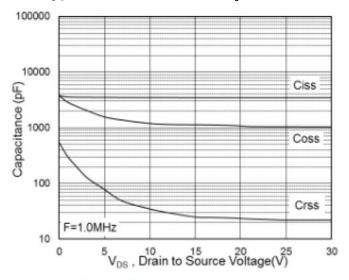


Fig. 6 Normalized RDSON v.s TJ



Typical Characteristics $T_J = 25$ °C, unless otherwise noted



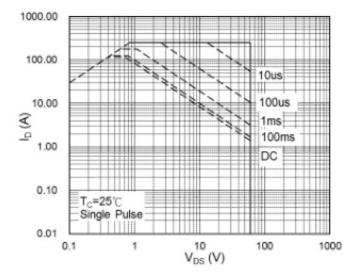


Fig.7 Capacitance

Fig.8 Safe Operating Area

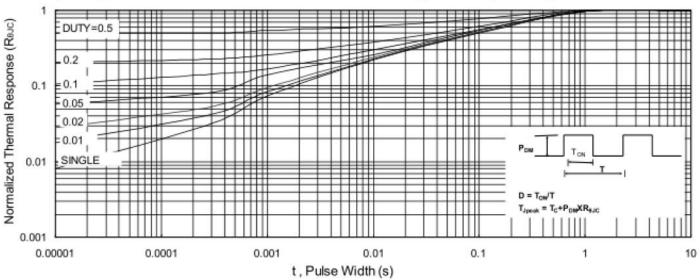


Fig.9 Normalized Maximum Transient Thermal Impedance



Figure A: Gate Charge Test Circuit and Waveform

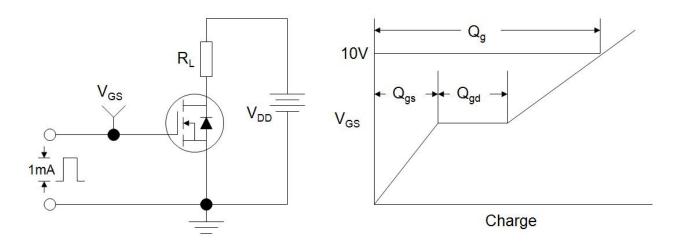


Figure B: Resistive Switching Test Circuit and Waveform

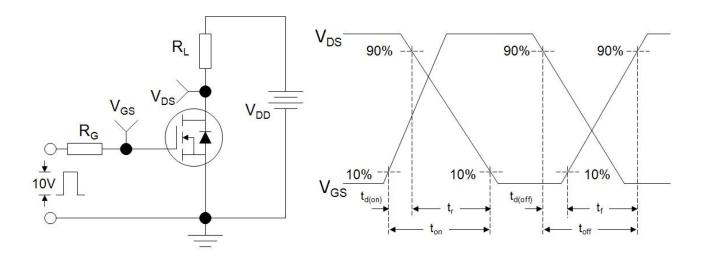
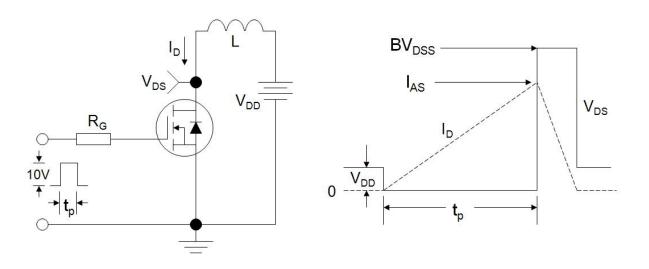
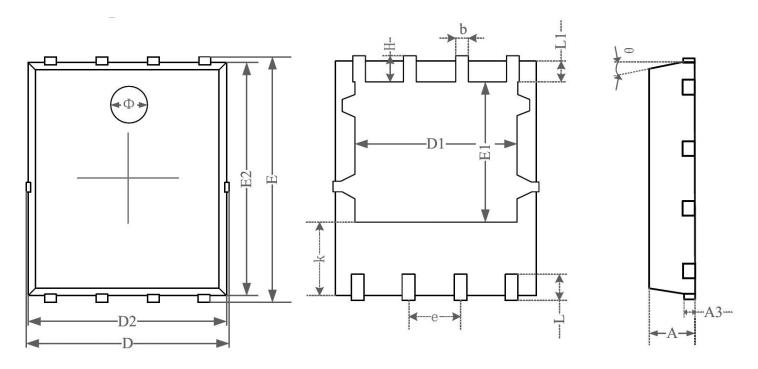


Figure C: Unclamped Inductive Switching Test Circuit and Waveform





DFN5*6



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES			
SYMBOLS	MIN	NOM	MAX	MIN	NOM	MAX	
A	0.870	0.900	0.930	0.034	0.035	0.036	
A3	0.152REF.			0.006REF.			
D	4.944	5.020	5.096	0.195	0.198	0.201	
Е	5.974	6.050	6.126	0.235	0.238	0.241	
DI	3.910	4.010	4.110	0.154	0.158	0.162	
E1	3.375	3.475	3.575	0.133	0.137	0.141	
D2	4.870	4.900	4.930	0.192	0.193	0.194	
E2	5.720	5.750	5.780	0.226	0.227	0.228	
k	1.190	1.290	1.390	0.047	0.051	0.055	
b	0.350	0.380	0.410	0.014	0.015	0.016	
e	1.270TYP.			20	0.050TYP.	5%	
L	0.559	0.635	0.711	0.022	0.025	0.028	
LI	0.424	0.500	0.576	0.017	0.020	0.023	
Н	0.574	0.650	0.726	0.023	0.026	0.029	
θ	10°	11°	12 °	10°	11°	12°	
Φ	1.150	1.200	1.250	0.045	0.047	0.049	



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